US00D655255S

(12) United States Design Patent
Takebayashi et al.

(10) **Patent No.:** **US D655,255 S**
(45) **Date of Patent:** ** **Mar. 6, 2012**

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(54) **BOAT OF WAFER PROCESSING APPARATUS**

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(**) Term: **14 Years**

(21) Appl. No.: **29/378,016**

(22) Filed: **Oct. 28, 2010**

(30) **Foreign Application Priority Data**

Jun. 18, 2010 (JP) 2010-015046

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/182; D15/144, 144.1, 199; 118/715; 211/41.18; 432/253, 258
See application file for complete search history.

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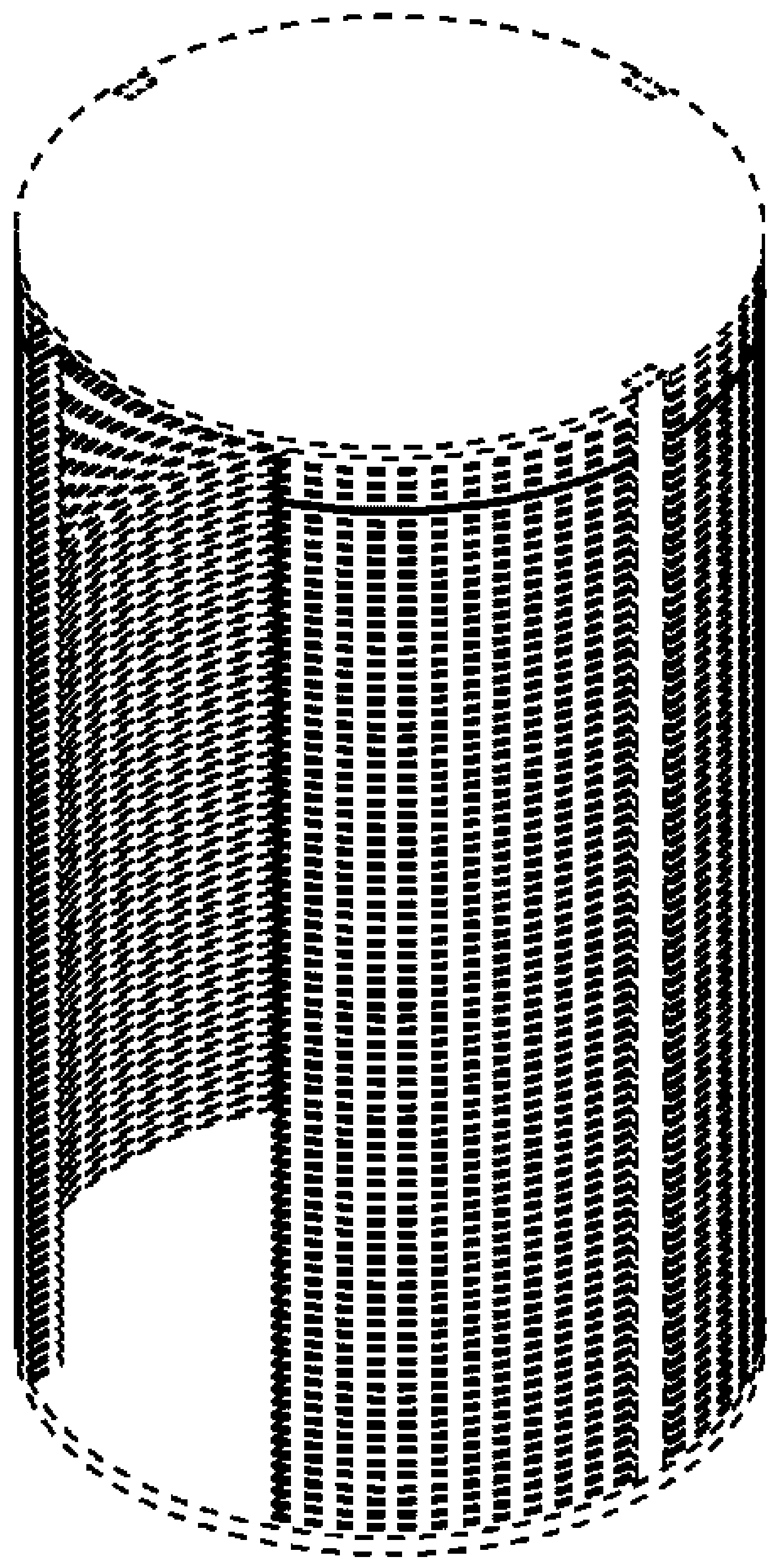
(57) **CLAIM**

The ornamental design for a boat of a wafer processing apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view **1** of a boat of the wafer processing apparatus;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a right side elevational view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof;
FIG. **8** is an enlarged cross-sectional view thereof taken along lines **8-8** in FIG. **2**;
FIG. **9** is a cross-sectional view thereof taken along lines **9-9** in FIG. **8**; and,
FIG. **10** is a perspective view of the cross-section from FIG. **9**.
The broken line showing of the boat of a wafer processing apparatus is for the purpose of illustrating environmental structure and forms no part of the claimed design.

1 Claim, 10 Drawing Sheets



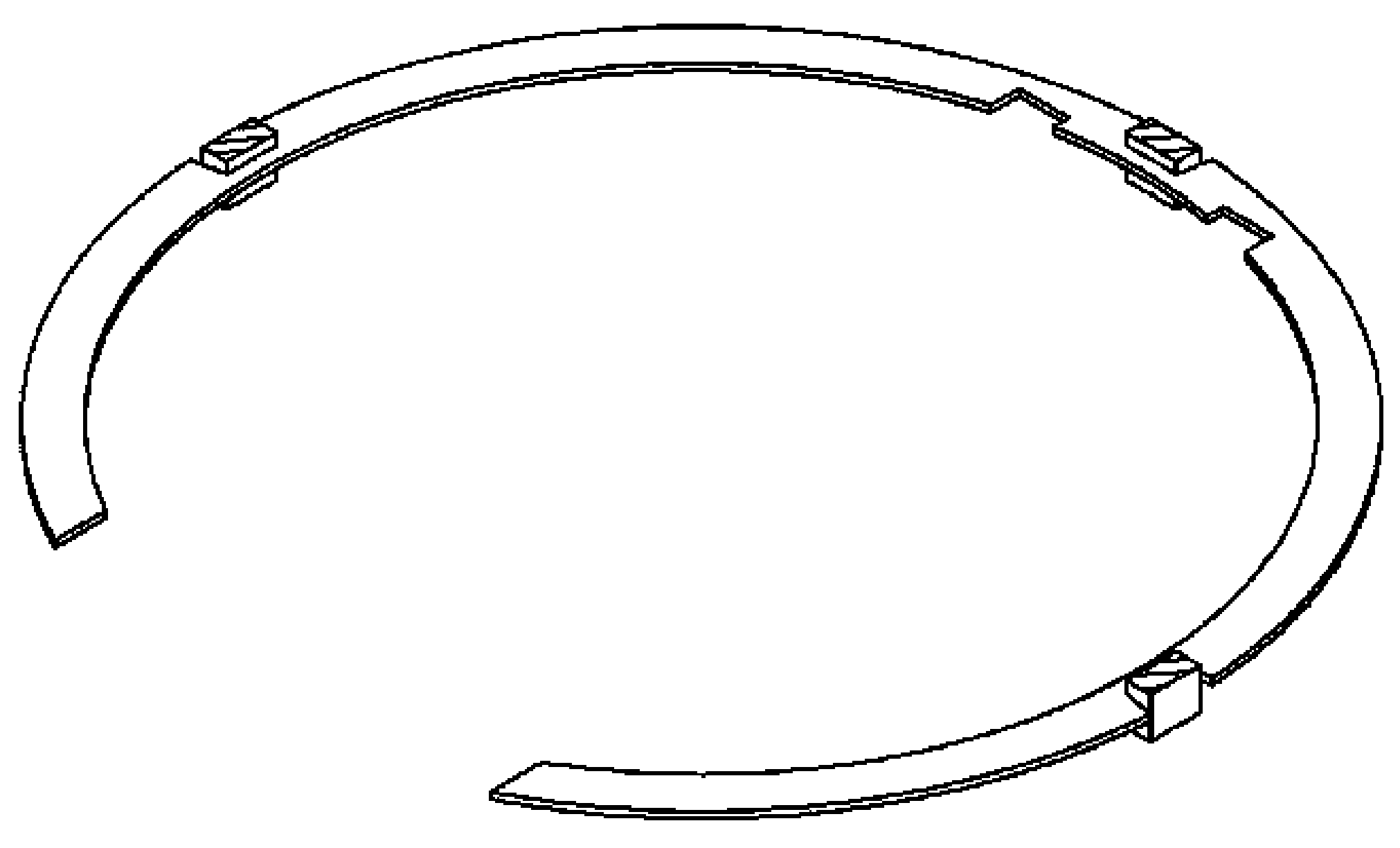


Fig. 1

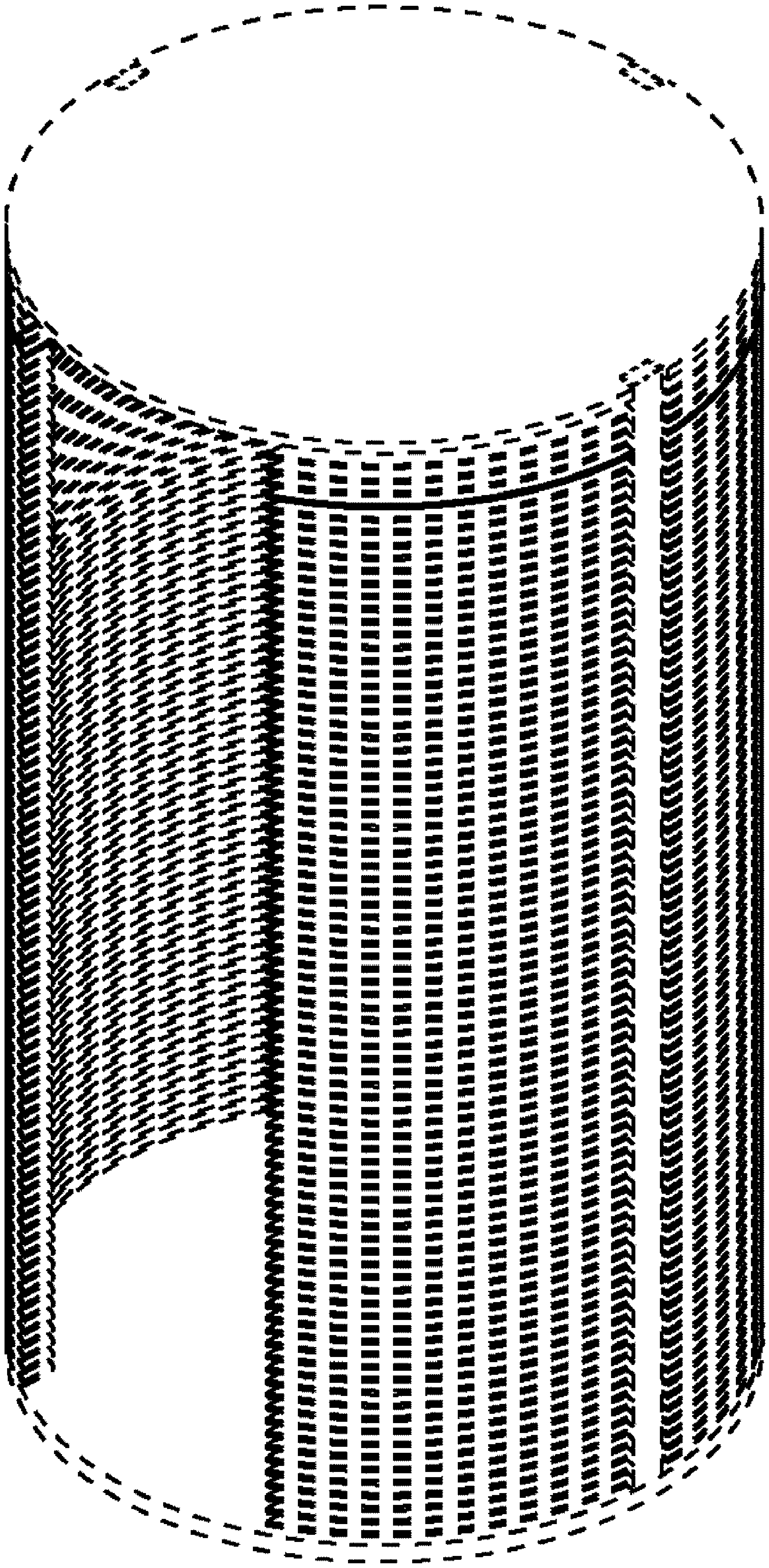


Fig. 2

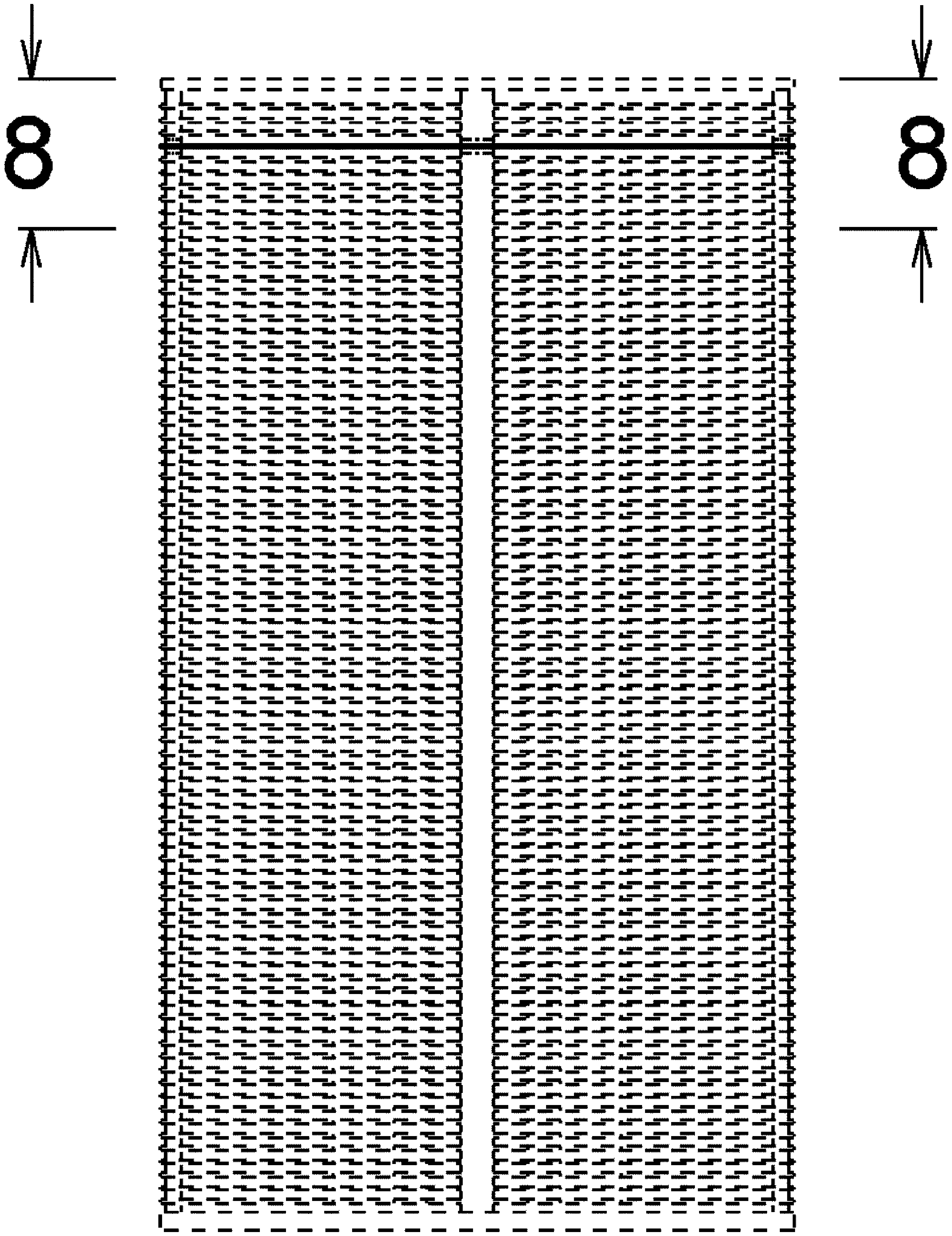


Fig. 3

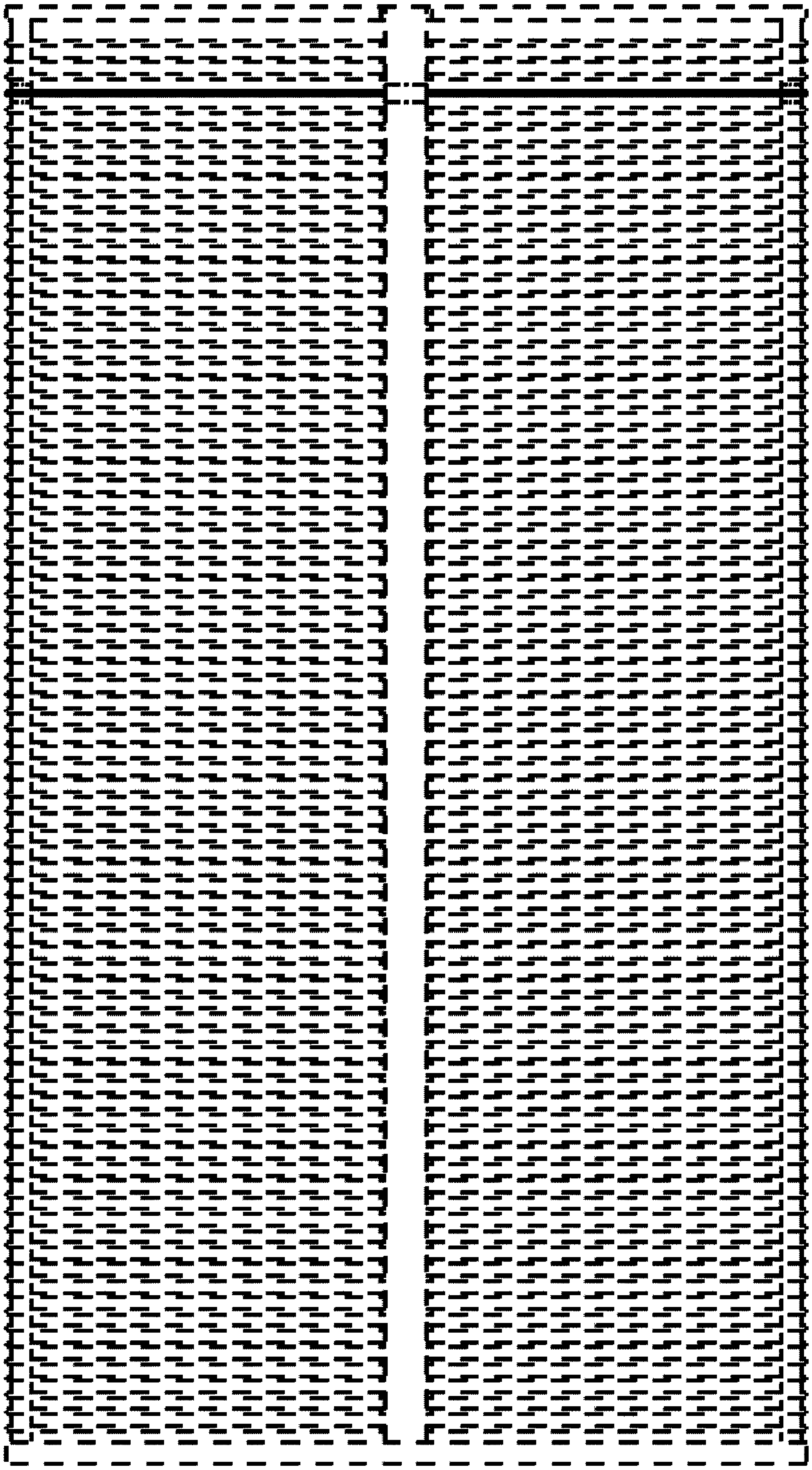


Fig. 4

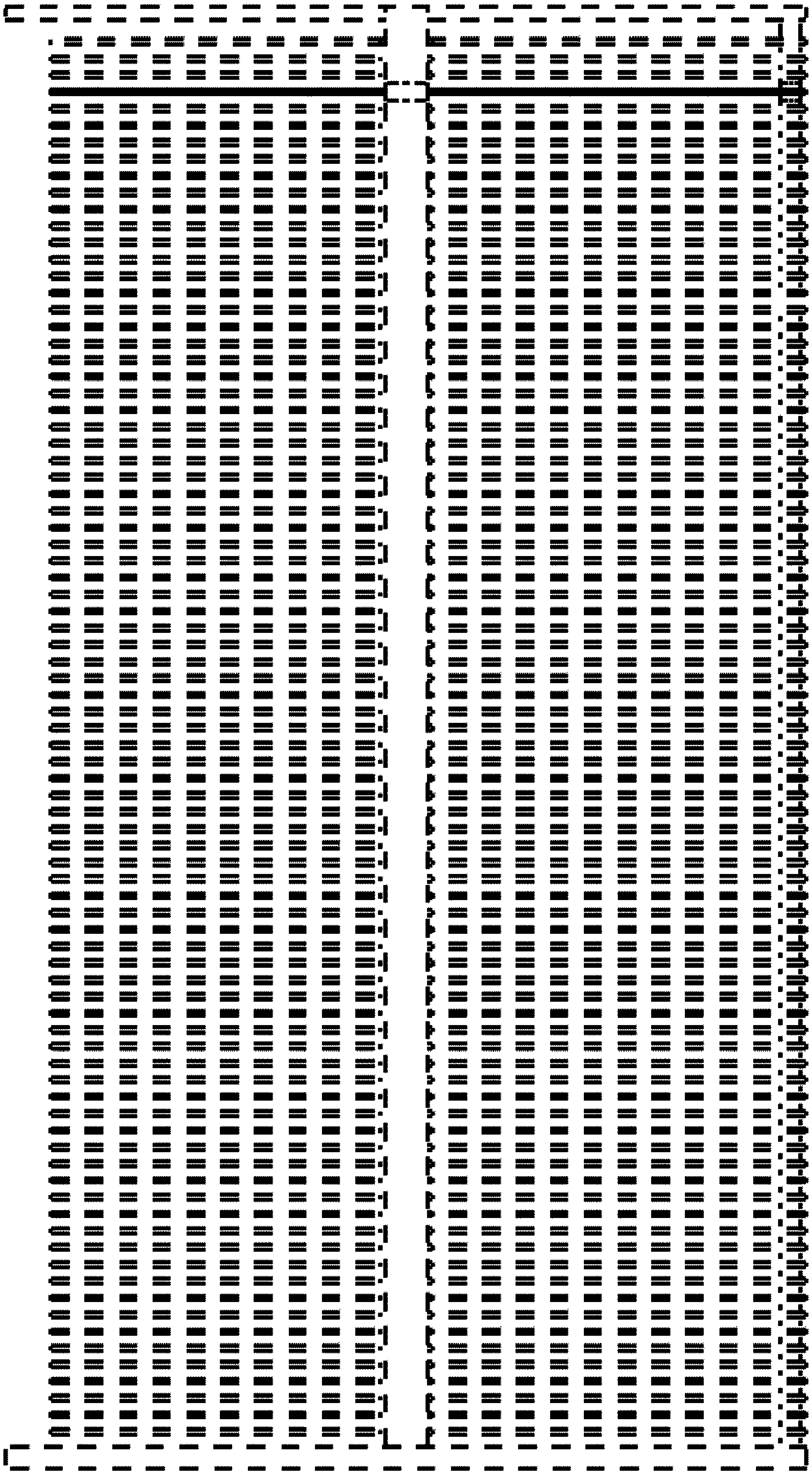


Fig. 5

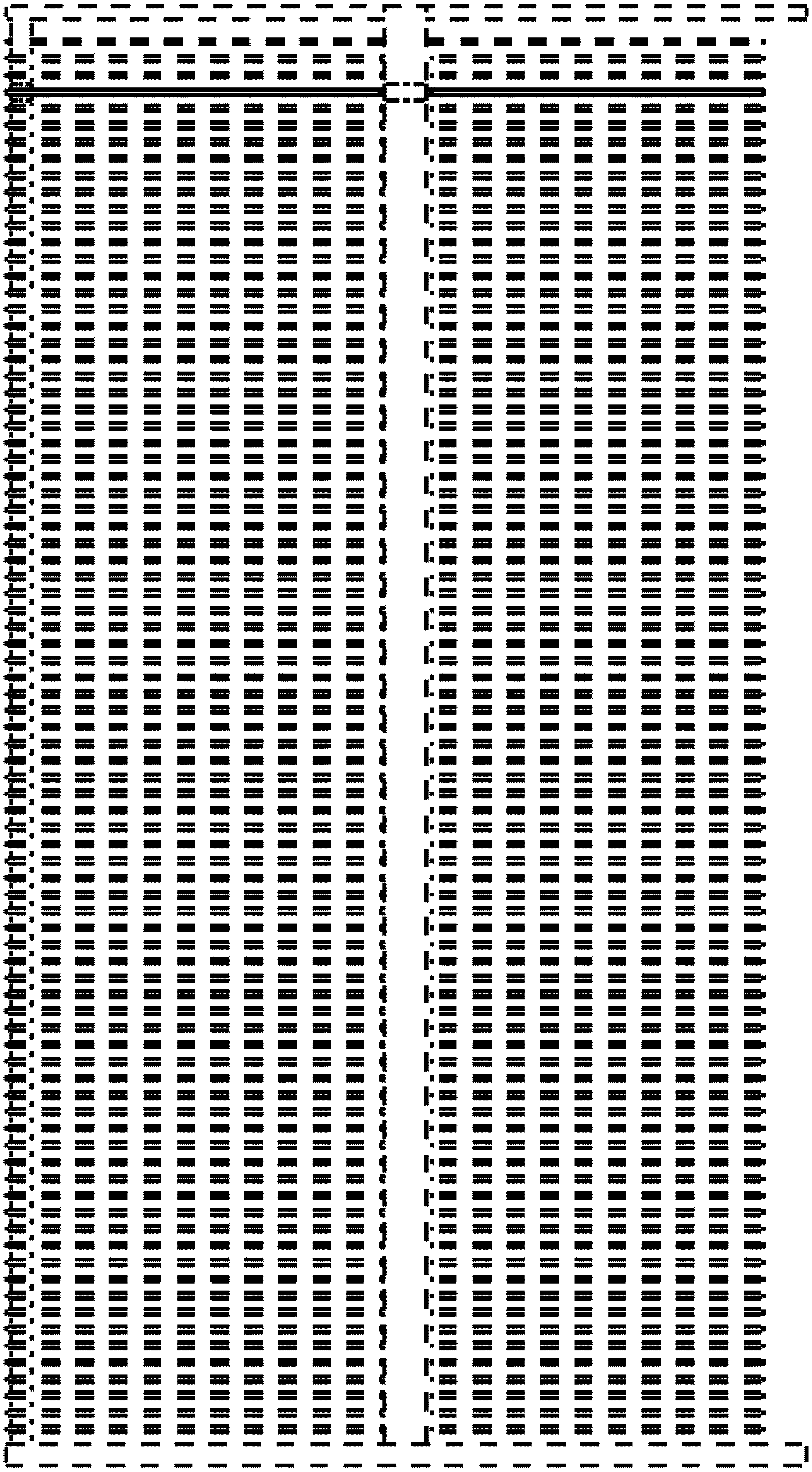


Fig. 6

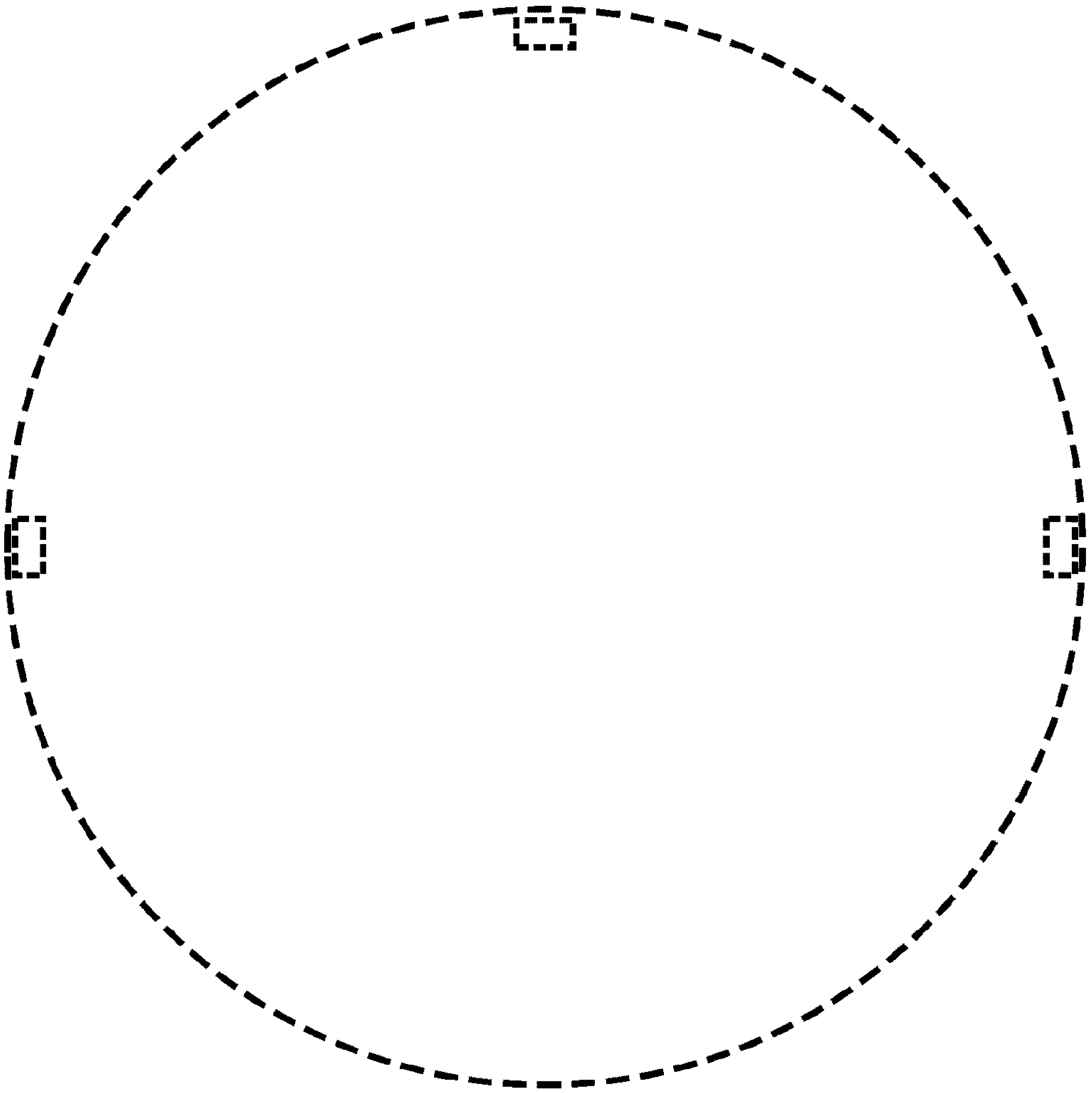


Fig. 7

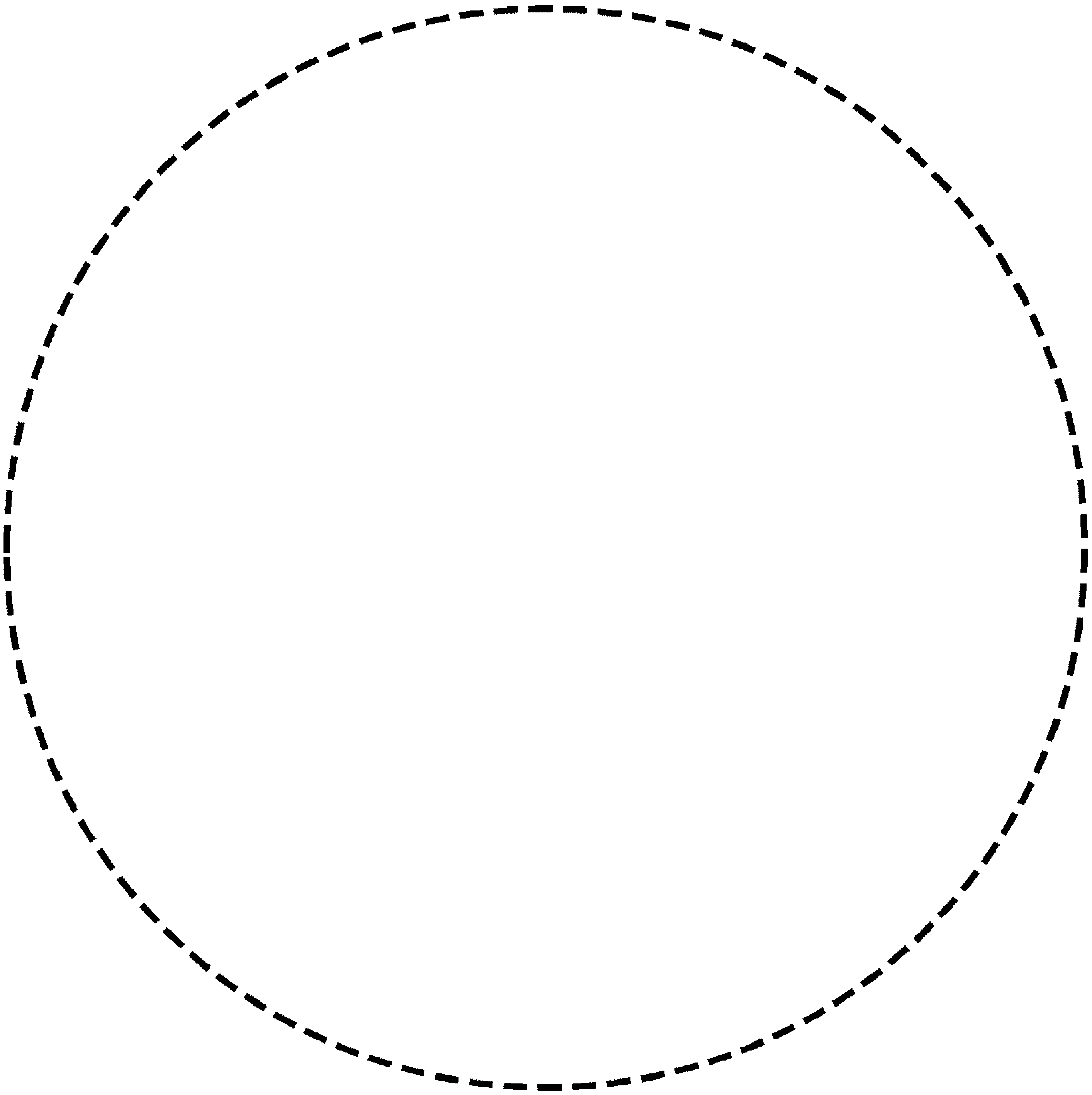


Fig. 8

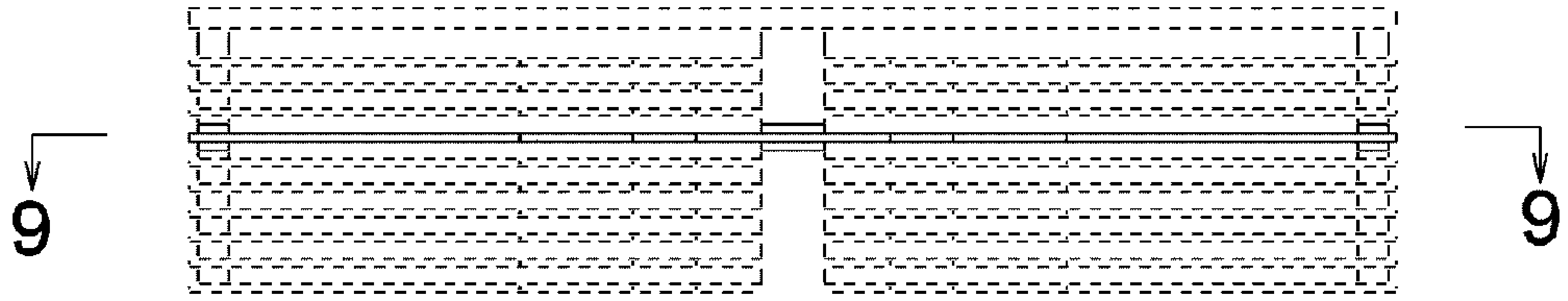


Fig. 9

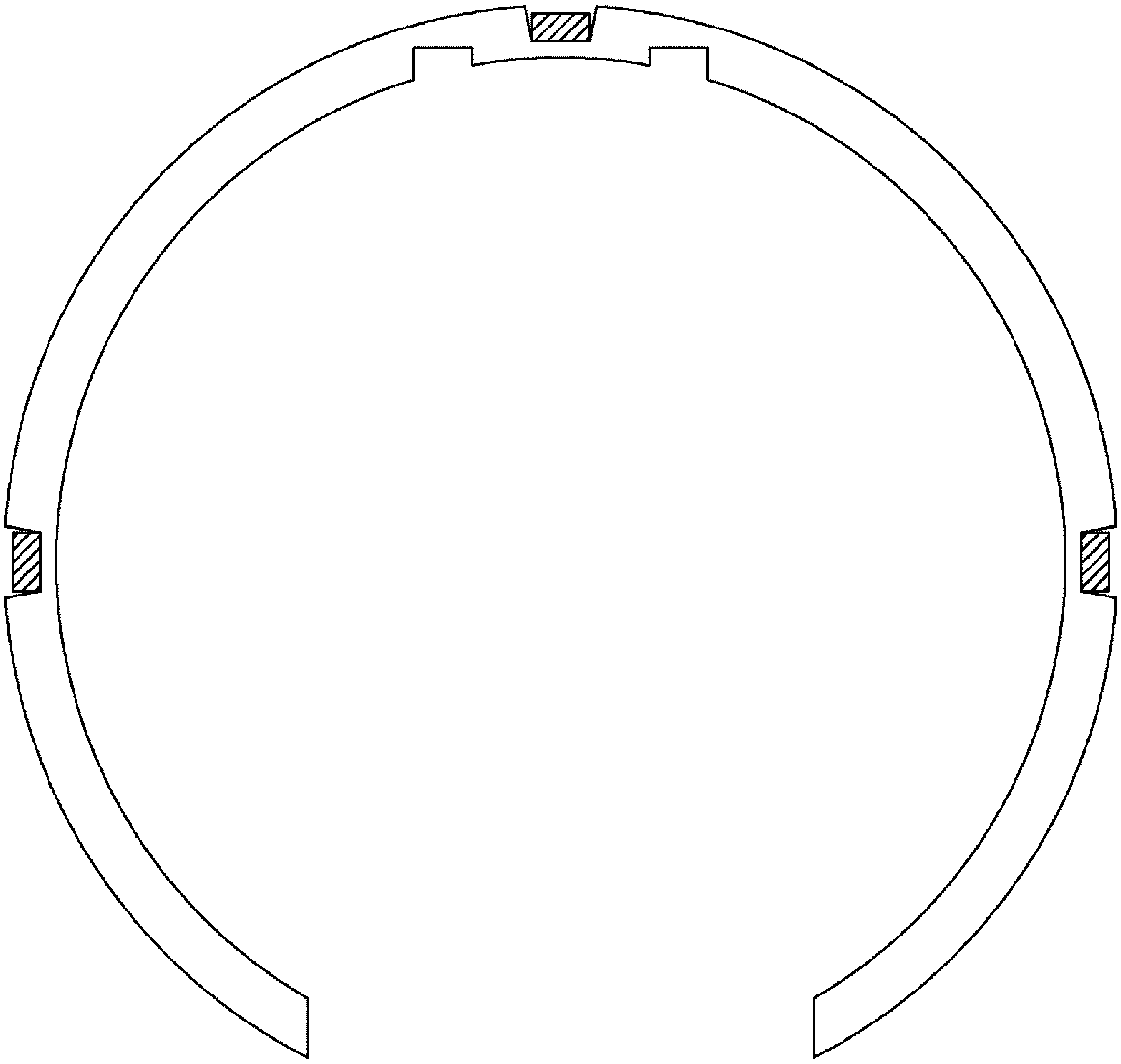


Fig. 10